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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/691,811	10/19/2000	Stanley W. Olson	BERG-2550/C2719	5391	
	7590 03/26/2003				
John P Dono	hue Jr Esq	EXAMINER			
Woodcock Wa	······	ABRAMS, NEIL			
Mackiewicz &					
One Liberty Place - 46th Floor Philadelphia, PA 19103			ART UNIT	PAPER NUMBER	
1 mau-pma, 2			2839		
			DATE MAILED: 03/26/2003		

Please find below and/or attached an Office communication concerning this application or proceeding.

•		Application No.		Applicant(s)	h		
Offic	Action Summary	09/691811 Examiner					
		M-	Abr	ams	Group Art Unit 2839		
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Status Responsive to	communication(s) filed on 2-18	-03	(R	$(\epsilon)a$	ind amount a	y 1-21-03	
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	ication is in condition for allowance except th the practice under <i>Ex parte Quayle</i> , 193				to the merits is o	closed in	
Disposition of Clair	ns 4n						
Claim(s) 13	-18, 42-46	is/are p	is/are pending in the application.				
Of the above cl	aim(s)	is/are v	is/are withdrawn from consideration.				
☐ Clạim(s)———	100			is/are a	is/are allowed.		
Claim(s) 15	1-18, 42-46	is/are r	is/are rejected.				
Claim(s)	,	is/are o	_ is/are objected to.				
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Application Papers		i		require			
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Atta hment(s)							
Information Dis	closure Statement(s), PTO-1449, Paper No	o(s)	_	terview Sum	mary, PTO-413		
<i>[.]</i>	ence(s) Cited, PTO-892	_			mal Patent Applic	ation, PTO-152	
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U.S. Patent and Trademark Office PTO-326 (Rev. 11/00)

Application/Control Number: 09/691,811

Art Unit: 2839

The request for continued examination (RCE) transmitted is acknowledged. A first action in such RCE follows.

Claims 15-19 and 42-46 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gaudenzi in view of LoVasco and Dozier and Japan 2-28990.

Gaudenzi, fig. 8, note 266 and hold down 58. A reflow step secures the contact and hold down to pcb 60 while due to large size of hole 62 the contact 56 is able to self center on a pad on pcb 60. Such self alignment of solder balls also taught by Dozier, col. 25, line 50 to col. 26, line 8, see discussion of loose pin alignment. Also obvious to form the pins of Gaudenzi, col. 6, lines 20-25 and in view of Japan patent, fig. 4 at 3 and use of stops in LoVasco at 432, etc.

This would prevent undue deformation of the solder balls and provide space for cooling. Reflow process is standard and further taught by LoVasco and Japan with single reflow for long and short pins, fig. 1. The large size of hole 62 could readily result in securement of pin 58 subsequent to attachment of solder balls 56. Compare fig. 8 to applicants fig. 6B. If application post 525 would cool more slowly than the solder balls (page 11) Gaudenzi post 58 should perform similarly. For article claims 42-46, the patents are similarly applied. Claim 42, lines 9, 10, "subsequent to" method limitation does not clearly define structural features of the product and cannot be relied upon to overcome the prior art. For claim 42, no "product limitation" is seen to define over Gaudenzi. If one is present it should be pointed out.

Claims 16-19, 43-46 define features shown by the prior art and do not appear to be at issue.

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Applicant's arguments filed with the amendment have been fully considered but they are not persuasive. See above discussion.

Any inquiry concerning this communication should be directed to N. Abrams at telephone number 308-1729.

Abrams/ek

03/21/03

M. Ole

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